

QMFF450R12XFF

1200V 450A IGBT Module

Electrical Features

- Trench/Fieldstop IGBT
- Low V_{CE}(sat)
- V_{CE}(sat) with positive temperature coefficient
- 10 µs short circuit capability
- Fast&soft reverse recovery anti-parallel FWD
- Low inductance case



Typical Applications

- Motor Drives
- UPS System
- Servo Drives
- Wind Turbines

IGBT, Inverter

Maximu	ım Rated Values						
Symbol	Item	Conditions			Rating		Unit
IGBT							
Vces	Collector-emitter voltage	T _{vj} =25°C	T_{vj} =25°C			1200	
V _{GES}	Gate-emitter voltage	-			±20		V
Ic	Collector current, DC	$T_{\rm C} = 100^{\circ}{\rm C}, T_{\rm vj} = 175^{\circ}{\rm C}$			45	450	
Icrm	Repetitive peak collector current	t _p =1ms			900		A
$t_{\rm SC}$	Short circuit withstand time	V _{GE} = 15V, V _{CC} =600V, T _V	_{′j} ≤150°C		10		μs
P _{tot}	Total power dissipation	$T_{C}=25^{\circ}C, T_{vj}=175^{\circ}C$			2586		W
Charact	eristics Values	1					
Symbol	Item	Conditions			Values		Unit
IGBT				Min.	Typ.	Max.	
Ices	Collector-emitter cut-off current	V _{CE} =1200V,V _{GE} =0V,T _{vj} =25°C		_	-	10	μА
I _{GES}	Gate leakage current	V _{CE} =0V,V _{GE} =20V,T _{vj} =25°C		-	-	50	nA
V _{GE(th)}	Gate-emitter threshold voltage	I _C =17.1mA,V _{CE} =V _{GE} ,T _{vj} =25°C		5.0	5.7	7.0	
	Collector-emitter saturation voltage	I _C =450A V _{GE} =15V	T _{vj} =25°C	-	2.13	-	1
V _{CEsat}			T _{vj} =125°C	-	2.60	-	V
. 02544			T _{vj} =150°C	-	2.68	-	
Cies	Input capacitance				31.8	-	
Coes	Output capacitance	V_{CE} =25V, V_{GE} =0V f=1MHz, T_{vj} =25°C		-	2.1	-	nF
Cres	Reverse transfer capacitance			-	1.08	-	
Q _G	Gate charge	$V_{GE} = \pm 15V$		-	2814	-	nC
Rg	Internal gate resistance	T _{vj} =25°C		-	0.4	-	Ω



			T _{vj} =25°C		126	_	
td(on)	Turn-on delay time		$T_{vj}=125$ °C	_	148	-	
	•		T _{vj} =150°C	_	152	_	
		$V_{\rm CC}=600\rm V$	T _{vj} =25°C	_	142	_	
$t_{\rm r}$	Rise time	I _C =450A	$T_{vi}=125$ °C	_	168	_	=
		$V_{GE}=\pm 15V$	$T_{vi} = 150$ °C	_	176	_	
		$R_{G(on)}=5.1 \Omega$	$T_{vi}=25^{\circ}C$	_	715	_	ns
$t_{d(off)}$	Turn-off delay time	$R_{G(off)}=5.1 \Omega$	$T_{vi}=125$ °C	_	783	_	
	•	L _{load} =50uH	T _{vj} =150°C	_	840	_	
		2.00.0 0 0.01	T _{vj} =25°C	-	121	_	
$t_{\rm f}$	Fall time		$T_{vi}=125$ °C	-	128	_	-
			$T_{vi} = 150^{\circ}C$	_	136	_	
		V _{CC} =600V , I _C =450A	T _{vj} =25°C	_	84.2	_	
Eon	Turn-on energy (per pulse)	$V_{GE}=\pm 15V$, $R_{G(on)}=5.1\Omega$	$T_{vj}=125^{\circ}C$	_	108.8	_	
20.1		$di/dt=3800A/\mu s(T_{vj}=150^{\circ}C)$	T _{vj} =150°C		116.8	_	
		V _{CC} =600V , I _C =450A	T _{vj} =25°C		47.7	_	mJ
E_{off}	Turn-off energy (per pulse)	$V_{GE}=\pm 15V$, $R_{G(off)}=5.1\Omega$	$T_{vi}=125^{\circ}C$		49.2	_	
Lon		$du/dt=6230V/\mu s(T_{vj}=150^{\circ}C)$	T _{vj} =150°C	_	52.5	_	-
		$V_{CC}=600V, V_{GE} \le 15V, T_{vj}=25^{\circ}$					
SC data	Short-circuit current	V _{CES} ≤1200V,tp≤10μs		-	2388	-	A
R _{thJC}	Thermal resistance, junction to case	per IGBT		-	-	0.058	K/W
RthCH	Thermalresistance,case to heatsink	per IGBT/ λgrease=1W/(m·I	K)	-	0.03	-	K/W
T _{vjop}	Temperature under switching condit	ions		-40		150	°C
	Inverter						ı
Maxim	um Rated Values						
Symbol	Item	Conditions			Rating		Unit
Vrrm	Repetitive peak reverse voltage	T _{vj} =25°C			1200		V
I_{F}	Forward current,DC	T _C =100°C,T _{vj} =150°C	$T_{\rm C} = 100^{\circ}{\rm C}, T_{\rm vj} = 150^{\circ}{\rm C}$			450	
I _{FRM}	Repetitive peak forward current	$t_p=1$ ms			900		A
I ² t	I ² t-value	$V_R=0V, t_p=10ms, T_{vj}=150$ °C			28500		A^2s
Charac	teristic Values						
			T 0.50C				
$V_{\scriptscriptstyle F}$		1 4504	$T_{vj}=25$ °C	-	2.19	-	I
$V_{\rm F}$	Continuous forward voltage	I _F =450A	$T_{vj} = 25^{\circ}C$ $T_{vj} = 125^{\circ}C$	-	2.19	-	V
V_{F}	Continuous forward voltage	I _F =450A V _{GE} =0V		- -		-	V
V _F	Continuous forward voltage		T _{vj} =125°C	-	2.08	- - -	V
	Continuous forward voltage Peak reverse recovery current		T_{vj} = 125°C T_{vj} = 150°C	-	2.08	-	V
$V_{\rm F}$ $I_{\rm RM}$	-		T_{vj} = 125°C T_{vj} = 150°C T_{vj} =25°C		2.08 2.02 183		
	-	V _{GE} =0V	T_{vj} = 125°C T_{vj} = 150°C T_{vj} = 25°C T_{vj} = 125°C	- - -	2.08 2.02 183 259		
I_{RM}	-	V_{GE} =0V V_{R} =600V	T_{vj} = 125°C T_{vj} = 150°C T_{vj} =25°C T_{vj} = 125°C T_{vj} = 150°C	- - -	2.08 2.02 183 259 284		
	Peak reverse recovery current	V_{GE} =0V V_{R} =600V I_{F} =450A	$T_{vj}=125^{\circ}C$ $T_{vj}=150^{\circ}C$ $T_{vj}=25^{\circ}C$ $T_{vj}=125^{\circ}C$ $T_{vj}=150^{\circ}C$ $T_{vj}=25^{\circ}C$	- - - -	2.08 2.02 183 259 284 175	- - - -	A
I_{RM}	Peak reverse recovery current	V_{GE} =0V V_{R} =600V I_{F} =450A V_{GE} =-15V	$T_{vj}=125^{\circ}C$ $T_{vj}=150^{\circ}C$ $T_{vj}=25^{\circ}C$ $T_{vj}=125^{\circ}C$ $T_{vj}=150^{\circ}C$ $T_{vj}=25^{\circ}C$ $T_{vj}=25^{\circ}C$ $T_{vj}=125^{\circ}C$	- - - - -	2.08 2.02 183 259 284 175 421	- - - -	A
I_{RM}	Peak reverse recovery current	$V_{GE}\!\!=\!\!0V$ $V_{R}\!\!=\!\!600V$ $I_{F}\!\!=\!\!450A$ $V_{GE}\!\!=\!\!-15V$ $-di_{F}/dt\!\!=\!\!3500A/\mu s$	$T_{vj}=125^{\circ}C$ $T_{vj}=150^{\circ}C$ $T_{vj}=25^{\circ}C$ $T_{vj}=125^{\circ}C$ $T_{vj}=150^{\circ}C$ $T_{vj}=25^{\circ}C$ $T_{vj}=125^{\circ}C$ $T_{vj}=150^{\circ}C$ $T_{vj}=150^{\circ}C$	- - - - -	2.08 2.02 183 259 284 175 421 590	- - - -	A



Erec			T _{vj} =25°C	-	8 36	-	
	Reverse recovery energy		$T_{vj}=125^{\circ}C$	-	20.2	-	mJ
			T_{vj} = 150°C	-	29.3	-	
R _{thJC}	Thermal resistance, junction to case	per diode		-	-	0.1	K/W
R_{thCH}	Thermalresistance,case to heatsink	per diode/ λgrease=1W/(m·K)		-	0.045	-	K/W
T _{vjop}	Temperature under switching conditions		-40		150	°C	

NTC Thermistor Characteristics

Symbol	Item	Con l'aliana	Values			
	item Con	Conditions	Min.	Тур.	Max.	
R ₂₅	Rated resistance	Tc=25°C	-	5	-	kΩ
$\Delta R/R$	Deviation of resistance	$T_{C}=100^{\circ}\text{C}, R_{100}=493\Omega$	-5	-	5	%
P ₂₅	Power dissipation	T _C =25°C	-	-	20	mW
B _{25/50}	B-constant	$R_2=R_{25}exp[B_{25/50}(1/T_2-1/(298.15K))$	-	3375	-	
B _{25/80}	B-constant	$R_2=R_{25}exp[B_{25/80}(1/T_2-1/(298.15K))$	-	3411	-	K
B _{25/100}	B-constant	$R_2=R_{25}\exp[B_{25/100}(1/T_2-1/(298.15K))]$	-	3433	-	

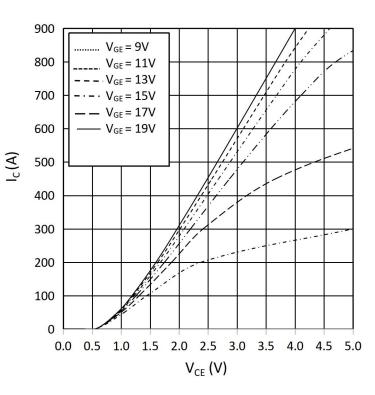
Module

Symbol	Item	Conditions	Rating		Unit	
V _{ISOL}	Isolation voltage	Terminals to baseplate, RMS,f=50Hz,t=1min	2500			V
-	Material of module baseplate	-	Cu		-	
-	Internal isolation	Basic insulation(class 1, IEC 61140)	Al ₂ O ₃			-
T _{stg}	Storage temperature	-	-40~125		°C	
	Th	G. Tri		Values		Unit
Symbol	Item Conditions	Conditions	Min. Typ. Max.			
M	Mounting torque for module mounting	Screw M6	3.0	-	5.0	Nm
	Terminal connection torque	Screw M6	2.5	-	5.0	Nm
ds	Creepage distance	Terminal to terminal	-	13	-	
		Terminal to base plate	-	14.5	-	mm
da	Classic	Terminal to terminal	-	10	-	
	Clearance	Terminal to base plate	-	12.5	-	mm
m	Weight	-	-	340	-	g



output characteristic IGBT, Inverter (typical)

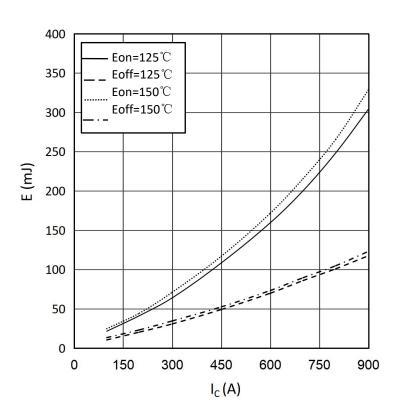
$$I_C = f(V_{CE})$$



switching losses IGBT,Inverter(typical)

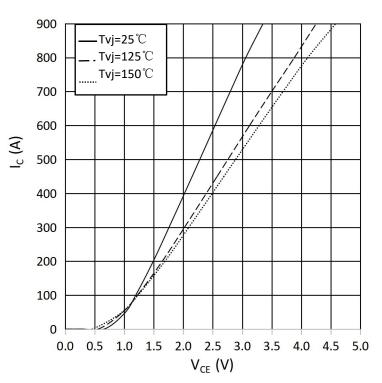
$$E_{on} = f(I_C), E_{off} = f(I_C)$$

$$V_{GE} = \pm 15V$$
, $R_{Gon} = 5.1\Omega$, $R_{Goff} = 5.1\Omega$, $V_{CE} = 600V$



output characteristic IGBT, Inverter (typical)

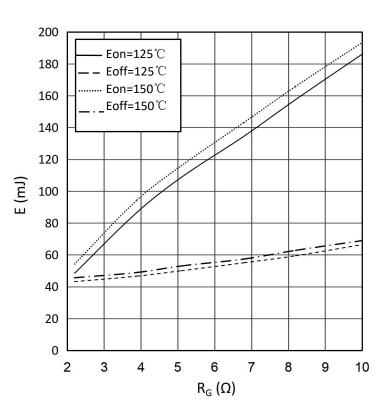
$$I_C = f(V_{CE})$$



switching losses IGBT,Inverter(typical)

$$E_{on} = f(R_G), E_{off} = f(R_G)$$

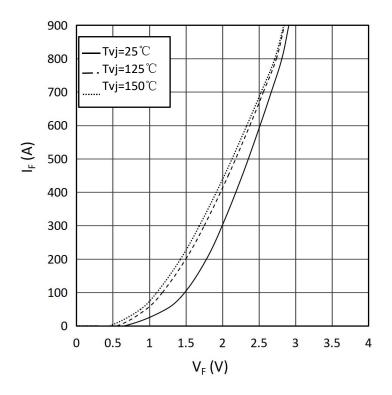
$$V_{GE} = \pm 15V$$
, $I_C = 450A$, $V_{CE} = 600V$





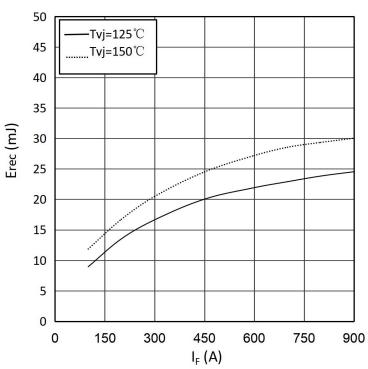
forward characteristic of Diode, Inverter (typical)

$$I_F = f(V_F)$$



switching losses Diode, Inverter (typical)

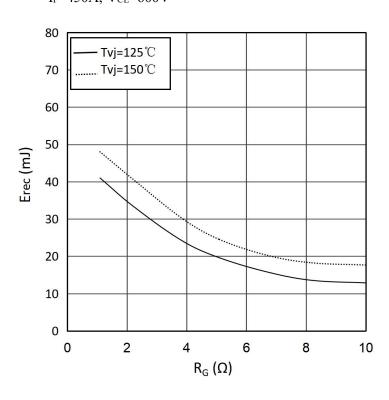
$$E_{rec} = f(I_F)$$



switching losses Diode, Inverter (typical)

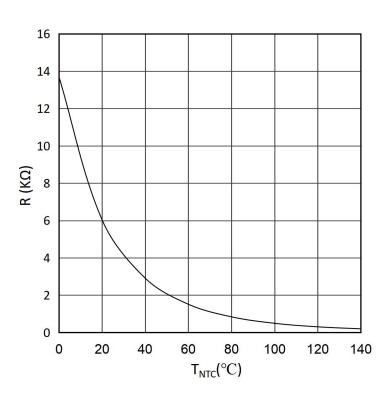
$$E_{rec} = f(R_G)$$

 $I_F=450A, V_{CE}=600V$



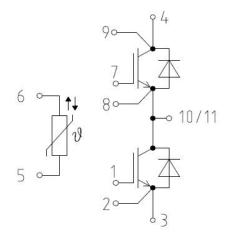
$NTC-Thermistor-temperature\ characteristic (typical)$

R=f(T)

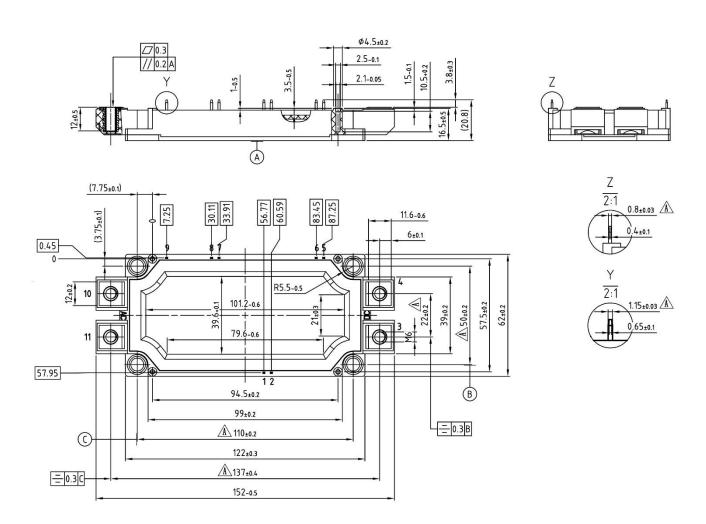




Circuit diagram headline



Package outlines (Unit: mm)





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